



DELTA X1 ZERO-HALOGEN NO-CLEAN LOW RESIDUE PASTE FLUX

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DESCRIPTION

Delta X1 is a Zero-Halogen, No-Clean flip-chip dipping paste flux especially formulated for extremely low residue. Its unique characteristic delivers better adhesion for underfills, and reduces possible outgassing during curing.

FEATURES

- Extremely low residue
- No-Clean
- Zero-Halogen
- Free from air entrapment
- Compatible with underfills

APPLICATION METHOD

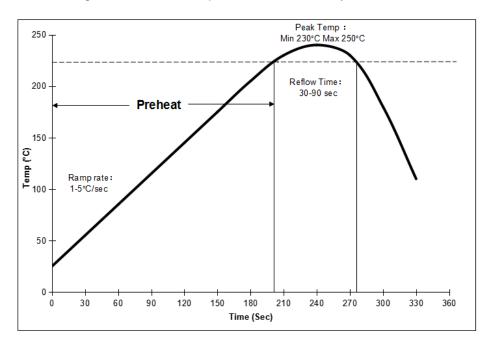
Dipping

PHYSICAL AND CHEMICAL PROPERTIES

PROPERTIES	SPECIFICATIONS	METHOD
Flux Classification	ROL0	IPC-J-STD-004B
Appearance	Light Amber	Visual
pH - 5% Aqueous Solution	6 - 8	QIT
Halide Content	Halide-Free	IPC-TM-650 2.3.33 (Silver Chromate Test)
Halogen Content	Zero-Halogen	EN 14582
Malcom Viscosity (@10rpm)	25 - 55 Pa.s	IPC-TM-650 2.4.34.3 (Modified)
Tack Strength	100 - 200 gf	JIS Z 3284
Surface Insulation Resistance	> 1.0 x 10 ⁹ ohms	IPC-TM-650 2.6.3.3
Post Reflow Flux Residue	< 10%	TGA Analysis

REFLOW

The following is a recommended profile for leadfree alloy:



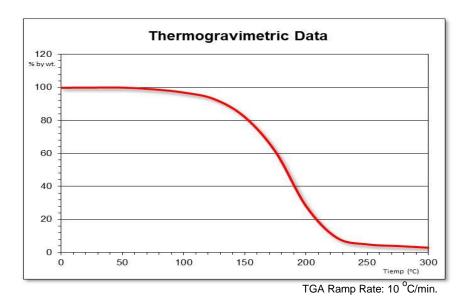
Reflow can be accomplished in a nitrogen controlled atmosphere at ≤ 100 ppm oxygen levels.

The initial ramp rate should be $1 - 5^{\circ}$ C per second to a peak temperature of $230 - 250^{\circ}$ C.

The time over liquidus temperature should be 30 - 90 seconds.

The profile is recommended to the user as reference, and should be optimized by the user to meet individual process needs.

THERMOGRAVIMETRIC DATA



FLUX RESIDUES & CLEANING

Delta X1 paste flux is a no-clean formulation therefore the residues are non-conductive and non-corrosive. If residue removal is desired, the use of ecofriendly aqueous cleaning chemistries can be used.

PACKAGING

Delta X1 paste flux is available in 10g and 30g syringes. Other packaging can be provided upon request.

STORAGE & HANDLING

Delta X1 may be stored at ambient temperature or refrigerated. Shelf life of paste flux is 6 month when stored at 2 to 25°C. If refrigerated, allow paste flux to reach ambient temperature prior to use.

SAFETY DATA SHEET

Contact Sales for SDS.